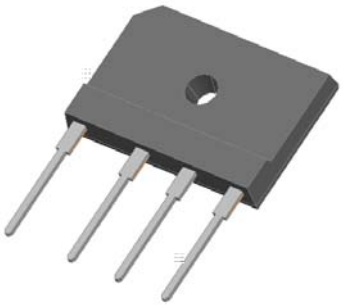
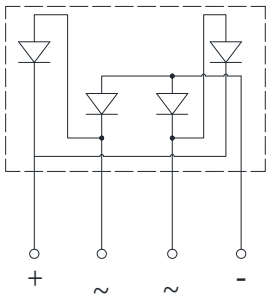
Low VF Bridge Rectifiers





Features

- UL recognition, file #E230084
- based on silicon planar process
- Low VF
- Thin single in-line package
- High surge current capability
- Solder dip 275 °C max. 7 s, per JESD 22-B106

Typical Applications

General purpose use in AC/DC bridge full wave rectification for switching power supply, home appliances, office equipment, industrial automation applications.

Mechanical Data

- **Package**: 6KBJ
  Molding compound meets UL 94 V-0 flammability rating, RoHS-compliant
- **Terminals**: Tin plated leads, solderable per

With heatsink
Tc =128

@60Hz sine wave, R-load

I_O

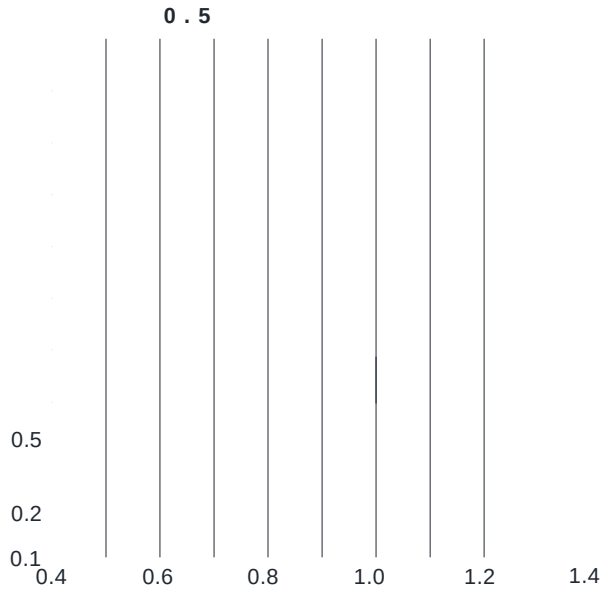
	Without heatsink Ta =25			3.2
Forward Surge Current (Non-repetitive) @60Hz Half-sine wave,1 cycle, Tj=25		I_{FSM}	A	250
Forward Surge Current (Non-repetitive) @1ms, square wave, 1 cycle, Tj=25				500
Current squared time @1ms≤t≤8.3ms Tj=25 , Rating of per diode		I^2t	A^2S	259.4
Storage temperature		T_{stg}		-55 ~ +150
Junction temperature		T_j		-55 ~ +150
Dielectric strength @ Terminals to case, AC 1 minute		V_{dis}	KV	2.5
Mounting torque @Recommend torque 5kg cm		Tor	kg cm	8

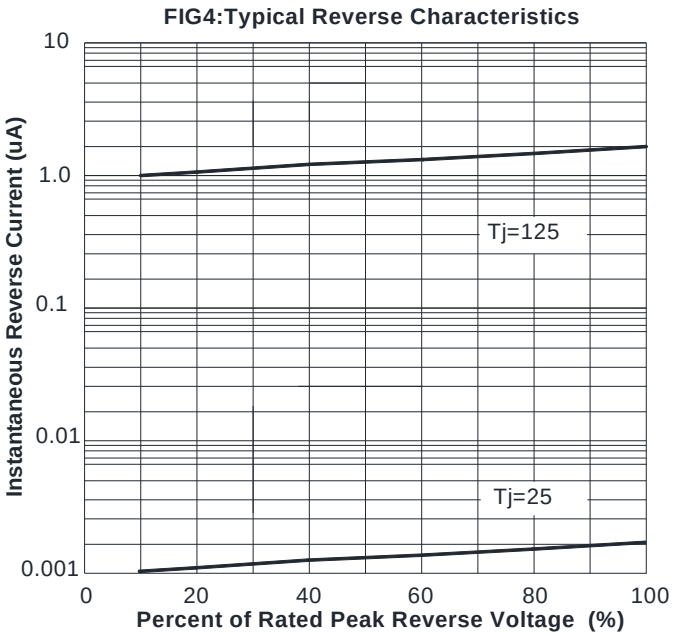
■Electrical Characteristics T_a=25 Unless otherwise specified

PARAMETER	SYMBOL	UNIT	TEST CONDITIONS	Min	Typ	Max
Instantaneous forward voltage drop per diode	V_F	V	I_{FM}=7.5A	0.80	0.875	0.92
DC reverse current at rated DC blocking voltage per diode	I_R	μA	T_j=25	-	0.001	5
			T_j=125	-	-	50
Junction capacitance	Cj	pF	Measured at 1MHz and Applied Reverse Voltage of 4.0 V.D.C	69	137	274

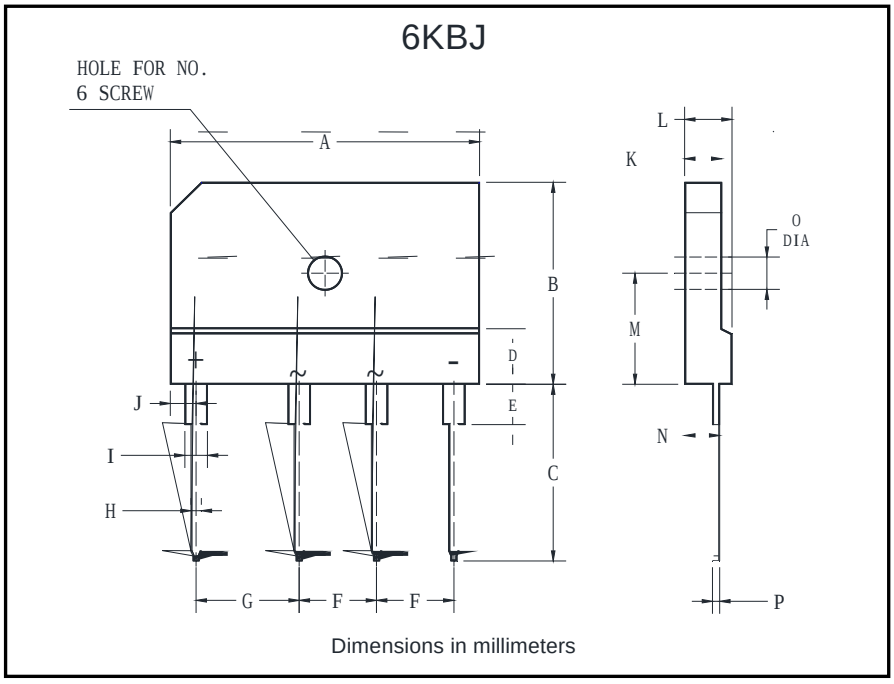
■Thermal Characteristics T_a=25 Unless otherwise specified

PARAMETER	SYMBOL	UNIT	GBJU1506
Between junction and ambient, Without heatsink	$R_{\theta J-A}$		
Typical Thermal Resistance		/W	





■ Outline Dimensions



6KBJ		
Dim	Min	Max
A	29.7	30.3
B	19.7	20.3
C	17.0	18.0
D	4.8	5.8
E	3.8	4.2
F	7.3	7.7
G	9.8	10.2
H	0.9	1.1
I	2.0	2.4
J	2.3	2.7
K	3.4	3.8
L	4.4	4.8
M	10.8	11.2
N	3.1	3.7
O	3.1	3.4
P	0.6	0.8

Disclaimer

The information presented in this document is for reference onl